



## Advance Product Change Notification

201405006A

**Issue Date:** 14-May-2014

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# QUALITY

### Management Summary

Change of bonding wire diameter from 25 µm to 18 µm for MFRC520, MFRC522, MFRC523

#### Change Category

- |  |  |   |  |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials          | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location           | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

Wire Diameter change for MFRC520, MFRC522, MFRC523

### Details of this Planned Change

NXP will change the bonding wire diameter for all MFRC520, MFRC522, MFRC523 types from currently 25 µm to 18µm. The change has been internally verified not to affect product functionality or reliability and after an internal release by NXP the change will be implemented. The qualification report is available on request.

#### Why do we Plan this Change

Following our material policy to improve quality and to standardize materials where possible in line with materials used in that location.

#### Identification of Affected Products

Product identification does not change

The Product identification does not change. Backwards traceability will be assured via date codes.

### Product Availability

#### Sample Information

Samples are available from 07-Jul-2014

#### Production

Planned first shipment 01-Sep-2014

#### Impact

no impact to the product's functionality anticipated.

## Data Sheet Revision

No impact to existing datasheet

## Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

The Self Qualification Report will be ready on 07-Jul-2014.

The Final PCN is planned to be issued on: 14-Jul-2014.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 13-Jun-2014.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

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